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1. Name of Conveying Party(ies):	2. Name and Address of Receiving Party(ies):				
(1) Hayato KOTANI(2) Naoyuki URASAKI and(3) Makoto MIZUTANI	Name: Hitachi Chemical Company, Ltd. Address: 1-1, Nishi Shinjuku 2-chome, Shinjuku-ku City: Tokyo Japan 163-0449				
Additional names of conveying parties attached: Yes No					
3. Nature of Conveyance:					
☑ Assignment ☐ Merger ☐ Security Agreement ☐ Change of Name ☐ Other:					
Execution Date: September 6, 2010					
4. (a) Patent Application Number(s):					
12/735,355	4. (b) Patent Numbers:				
If this document is being filed together with a new application, the execution date of the application is:					
☐ Additional Numbers Attached.					
5 5. Name and Address of Party to whom Correspondence	6. Total Number of Applications and Patents Involved:				
Concerning this Document Should be Mailed: Name: Juan Carlos A. Marquez	7. Total Fee: \$40.00 (37 C.F.R. § 3.41)				
Address: STITES & HARBISON, PLLC 1199 North Fairfax Street Suite 900	 ☑ Payment by credit card. Form PTO-2038 is attached. ☑ Authorized to be charged to deposit account. 				
Alexandria, VA 22314	8. Deposit Account Number: 12-0555				
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To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.					
September 20, 2010					
Juan Carlos A. Marquez, Registration No. 34,072					
Total number of pages comprising cover sheet: 1					

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PATENT REEL: 025027 FRAME: 0266

ASSIGNMENT

Whereas, I/we, Name Address ob HITACHI CHEMICAL COMPANY, LTD, 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan ob HITACHI CHEMICAL COMPANY, LTD, 2) Naoyuki URASAKI 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan ob HITACHI CHEMICAL COMPANY, LTD, 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan ob HITACHI CHEMICAL COMPANY, LTD, 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan ob HITACHI CHEMICAL COMPANY, LTD, 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan hereinafter called assignor(s), have invented certain improvements in THERMOSETTING RESIN COMPOSITION, EPOXY RESIN MOLDING MATERIAL, AND POLYVALENT CARBOXYLIG ACID CONDENSATE and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below. filed on		73310	I A I A I TO I A			
to HITACHI CHEMICAL COMPANY, LTD., 48, Wadai, Taukuba-shi, Ibaraki 300-4247 Japan ob HITACHI CHEMICAL COMPANY, LTD., 48, Wadai, Taukuba-shi, Ibaraki 300-4247 Japan ob HITACHI CHEMICAL COMPANY, LTD., 48, Wadai, Taukuba-shi, Ibaraki 300-4247 Japan ob HITACHI CHEMICAL COMPANY, LTD., 48, Wadai, Taukuba-shi, Ibaraki 300-4247 Japan hereinafter called assignor(s), have invented certain improvements in THERMOSETTING RESIN COMPOSITION, EPOXY RESIN MOLDING MATERIAL, AND POLYVALENT CARBOXYLIG ACID CONDENSATE and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below: filed on July 8, 2010 , Serial No. 12/735355 , and Whereas HITACHI CHEMICAL COMPANY, LTD. 1-1, Nishi-Shinjuku 2-chome, Shinjuku-ku, Tokyo 163-0449 Japan (assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor; NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, IWE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in an this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and IWE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense	Whereas, I/we,					
1) Hayato KOTANI 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan do HITACHI CHEMICAL COMPANY, LTD., 2) Naoyuki URASAKI 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan do HITACH CHEMICAL COMPANY, LTD., 3) Makoto MIZUTANI 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan do HITACH CHEMICAL COMPANY, LTD., 48, Wadai, Tsukuba-shi, Ibaraki 300-4247 Japan hereinafter called assignor(s), have invented certain improvements in THERMOSETTING RESIN COMPOSITION, EPOXY RESIN MOLDING MATERIAL, AND POLYVALENT CARBOXYLIC ACID CONDENSATE and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below: filed on	<u>Name</u>	A	ddress	•		
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(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)

Page 1 of 1

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